

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 09241518
PUBLICATION DATE : 16-09-97

APPLICATION DATE : 13-03-96
APPLICATION NUMBER : 08055904

APPLICANT : FUJITSU LTD;

INVENTOR : YAMAGUCHI JO;



INT.CL. : C08L101/00 C08K 3/36 C08L 83/16
C09D183/16 C09D201/00 H01L 21/312
H01L 21/768

TITLE : RESIN COMPOSITION AND METHOD
FOR FORMING MULTILAYER
INTERCONNECTION

ABSTRACT : PROBLEM TO BE SOLVED: To provide a material which can be applied by spin coating, is liquefied at relatively low temps. thus being able to become flat in the chip scale, can be formed into a film by the spin coating method capable of gap filling. and can provide a thermally cured insulating film having a permittivity of 2.5 or lower and to provide a method for forming such an insulating film.

SOLUTION: This resin compsn. for forming a multilayer interconnection comprises a high-molecular substance which can be thermally liquefied and cross-linked to become insol. and a silica sol or comprises a binder resin and fine tetrafluoroethylene polymer particles. The compsn. is applied onto a wiring board and thermally treated to form a flat insulating film.

COPYRIGHT: (C)1997,JPO

BEST AVAILABLE COPY